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Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx340f512h-80v-mr

PIC32MX3XX/4XX

TABLE 3: PIN NAMES: PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F128L, AND PIC32MX360F512L DEVICES

Pin Number	Full Pin Name
A1	PMD4/RE4
A2	PMD3/RE3
A3	TRD0/RG13
A4	PMD0/RE0
A5	PMD8/RG0
A6	PMD10/RF1
A7	ENVREG
A8	Vss
A9	IC5/PMD12/RD12
A10	OC3/RD2
A11	OC2/RD1
B1	No Connect (NC)
B2	RG15
B3	PMD2/RE2
B4	PMD1/RE1
B5	TRD3/RA7
B6	PMD11/RF0
B7	VCAP/VCORE
B8	PMRD/CN14/RD5
B9	OC4/RD3
B10	Vss
B11	SOSCO/T1CK/CN0/RC14
C1	PMD6/RE6
C2	VDD
C3	TRD1/RG12
C4	TRD2/RG14
C5	TRCLK/RA6
C6	No Connect (NC)
C7	PMD15/CN16/RD7
C8	OC5/PMWR/CN13/RD4
C9	VDD
C10	SOSCI/CN1/RC13
C11	IC4/PMCS1/PMA14/RD11
D1	T2CK/RC1
D2	PMD7/RE7
D3	PMD5/RE5
D4	Vss
D5	Vss
D6	No Connect (NC)
D7	PMD14/CN15/RD6
D8	PMD13/CN19/RD13
D9	OC1/RD0
D10	No Connect (NC)
D11	IC3/PMCS2/PMA15/RD10
E1	T5CK/RC4
E2	T4CK/RC3
E3	SCK2/PMA5/CN8/RG6
E4	T3CK/RC2
E5	VDD
E6	PMD9/RG1
E7	Vss

Pin Number	Full Pin Name
E8	INT4/RA15
E9	RTCC/IC1/RD8
E10	IC2/RD9
E11	INT3/RA14
F1	MCLR
F2	SDO2/PMA3/CN10/RG8
F3	SS2/PMA2/CN11/RG9
F4	SDI2/PMA4/CN9/RG7
F5	Vss
F6	No Connect (NC)
F7	No Connect (NC)
F8	VDD
F9	OSC1/CLKI/RC12
F10	Vss
F11	OSC2/CLKO/RC15
G1	INT1/RE8
G2	INT2/RE9
G3	TMS/RA0
G4	No Connect (NC)
G5	VDD
G6	Vss
G7	Vss
G8	No Connect (NC)
G9	TDO/RA5
G10	SDA2/RA3
G11	TDI/RA4
H1	AN5/C1IN+/CN7/RB5
H2	AN4/C1IN-/CN6/RB4
H3	Vss
H4	VDD
H5	No Connect (NC)
H6	VDD
H7	No Connect (NC)
H8	SDI1/RF7
H9	SCK1/INT0/RF6
H10	SCL1/RG2
H11	SCL2/RA2
J1	AN3/C2IN+/CN5/RB3
J2	AN2/C2IN-/SS1/CN4/RB2
J3	PGED2/AN7/RB7
J4	AVDD
J5	AN11/PMA12/RB11
J6	TCK/RA1
J7	AN12/PMA11/RB12
J8	No Connect (NC)
J9	No Connect (NC)
J10	SDO1/RF8
J11	SDA1/RG3
K1	PGEC1/AN1/CN3/RB1
K2	PGED1/AN0/CN2/RB0
K3	VREF+/CVREF+/PMA6/RA10

PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number ⁽¹⁾			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
AN0	16	25	K2	I	Analog	Analog input channels.
AN1	15	24	K1	I	Analog	
AN2	14	23	J2	I	Analog	
AN3	13	22	J1	I	Analog	
AN4	12	21	H2	I	Analog	
AN5	11	20	H1	I	Analog	
AN6	17	26	L1	I	Analog	
AN7	18	27	J3	I	Analog	
AN8	21	32	K4	I	Analog	
AN9	22	33	L4	I	Analog	
AN10	23	34	L5	I	Analog	
AN11	24	35	J5	I	Analog	
AN12	27	41	J7	I	Analog	
AN13	28	42	L7	I	Analog	
AN14	29	43	K7	I	Analog	
AN15	30	44	L8	I	Analog	
CLKI	39	63	F9	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	40	64	F11	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	39	63	F9	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	40	64	F11	I/O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	47	73	C10	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	48	74	B11	O	—	32.768 kHz low-power oscillator crystal output.

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer

Analog = Analog input P = Power
O = Output I = Input

Note 1: Pin numbers are provided for reference only. See the “Pin Diagrams” section for device pin availability.

2.11 Referenced Sources

This device data sheet is based on the following individual chapters of the *"PIC32 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the PIC32MX460F512L product page on the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **Section 1. "Introduction"** (DS61127)
- **Section 2. "CPU"** (DS61113)
- **Section 3. "Memory Organization"** (DS61115)
- **Section 4. "Prefetch Cache"** (DS61119)
- **Section 5. "Flash Program Memory"** (DS61121)
- **Section 6. "Oscillator Configuration"** (DS61112)
- **Section 7. "Resets"** (DS61118)
- **Section 8. "Interrupt Controller"** (DS61108)
- **Section 9. "Watchdog Timer and Power-up Timer"** (DS61114)
- **Section 10. "Power-Saving Features"** (DS61130)
- **Section 12. "I/O Ports"** (DS61120)
- **Section 13. "Parallel Master Port (PMP)"** (DS61128)
- **Section 14. "Timers"** (DS61105)
- **Section 15. "Input Capture"** (DS61122)
- **Section 16. "Output Compare"** (DS61111)
- **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS61104)
- **Section 19. "Comparator"** (DS61110)
- **Section 20. "Comparator Voltage Reference (CVREF)"** (DS61109)
- **Section 21. "Universal Asynchronous Receiver Transmitter (UART)"** (DS61107)
- **Section 23. "Serial Peripheral Interface (SPI)"** (DS61106)
- **Section 24. "Inter-Integrated Circuit™ (I²C™)"** (DS61116)
- **Section 27. "USB On-The-Go (OTG)"** (DS61126)
- **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS61125)
- **Section 31. "Direct Memory Access (DMA) Controller"** (DS61117)
- **Section 32. "Configuration"** (DS61124)
- **Section 33. "Programming and Diagnostics"** (DS61129)

TABLE 4-5: INTERRUPT REGISTERS MAP FOR PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY⁽¹⁾

Virtual Address (BF88..#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>					—	—
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>			CS1IS<1:0>	0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>			CTIS<1:0>	0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>			OC1IS<1:0>	0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>			T1IS<1:0>	0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>			OC2IS<1:0>	0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>			T2IS<1:0>	0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>			OC3IS<1:0>	0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>			T3IS<1:0>	0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>			OC4IS<1:0>	0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>			T4IS<1:0>	0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>	0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>			T5IS<1:0>	0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>			CNIS<1:0>	0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>			U1IS<1:0>	0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>			CMP2IS<1:0>	0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMPIP<2:0>			PMPIS<1:0>	0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>			FSCMIS<1:0>	0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>			U2IS<1:0>	0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>			—	—	—	DMA2IP<2:0>			DMA2IS<1:0>	0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>			—	—	—	DMA0IP<2:0>			DMA0IS<1:0>	0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>			—	—	—	FCEIP<2:0>			FCEIS<1:0>	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET, and INV registers at their virtual addresses, plus offsets of 0x4, 0x8, and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

PIC32MX3XX/4XX

TABLE 7-1: INTERRUPT IRQ AND VECTOR LOCATION

Interrupt Source ⁽¹⁾	IRQ	Vector Number	Interrupt Bit Location			
Highest Natural Order Priority			Flag	Enable	Priority	Subpriority
CT – Core Timer Interrupt	0	0	IFS0<0>	IEC0<0>	IPC0<4:2>	IPC0<1:0>
CS0 – Core Software Interrupt 0	1	1	IFS0<1>	IEC0<1>	IPC0<12:10>	IPC0<9:8>
CS1 – Core Software Interrupt 1	2	2	IFS0<2>	IEC0<2>	IPC0<20:18>	IPC0<17:16>
INT0 – External Interrupt 0	3	3	IFS0<3>	IEC0<3>	IPC0<28:26>	IPC0<25:24>
T1 – Timer1	4	4	IFS0<4>	IEC0<4>	IPC1<4:2>	IPC1<1:0>
IC1 – Input Capture 1	5	5	IFS0<5>	IEC0<5>	IPC1<12:10>	IPC1<9:8>
OC1 – Output Compare 1	6	6	IFS0<6>	IEC0<6>	IPC1<20:18>	IPC1<17:16>
INT1 – External Interrupt 1	7	7	IFS0<7>	IEC0<7>	IPC1<28:26>	IPC1<25:24>
T2 – Timer2	8	8	IFS0<8>	IEC0<8>	IPC2<4:2>	IPC2<1:0>
IC2 – Input Capture 2	9	9	IFS0<9>	IEC0<9>	IPC2<12:10>	IPC2<9:8>
OC2 – Output Compare 2	10	10	IFS0<10>	IEC0<10>	IPC2<20:18>	IPC2<17:16>
INT2 – External Interrupt 2	11	11	IFS0<11>	IEC0<11>	IPC2<28:26>	IPC2<25:24>
T3 – Timer3	12	12	IFS0<12>	IEC0<12>	IPC3<4:2>	IPC3<1:0>
IC3 – Input Capture 3	13	13	IFS0<13>	IEC0<13>	IPC3<12:10>	IPC3<9:8>
OC3 – Output Compare 3	14	14	IFS0<14>	IEC0<14>	IPC3<20:18>	IPC3<17:16>
INT3 – External Interrupt 3	15	15	IFS0<15>	IEC0<15>	IPC3<28:26>	IPC3<25:24>
T4 – Timer4	16	16	IFS0<16>	IEC0<16>	IPC4<4:2>	IPC4<1:0>
IC4 – Input Capture 4	17	17	IFS0<17>	IEC0<17>	IPC4<12:10>	IPC4<9:8>
OC4 – Output Compare 4	18	18	IFS0<18>	IEC0<18>	IPC4<20:18>	IPC4<17:16>
INT4 – External Interrupt 4	19	19	IFS0<19>	IEC0<19>	IPC4<28:26>	IPC4<25:24>
T5 – Timer5	20	20	IFS0<20>	IEC0<20>	IPC5<4:2>	IPC5<1:0>
IC5 – Input Capture 5	21	21	IFS0<21>	IEC0<21>	IPC5<12:10>	IPC5<9:8>
OC5 – Output Compare 5	22	22	IFS0<22>	IEC0<22>	IPC5<20:18>	IPC5<17:16>
SPI1E – SPI1 Fault	23	23	IFS0<23>	IEC0<23>	IPC5<28:26>	IPC5<25:24>
SPI1TX – SPI1 Transfer Done	24	23	IFS0<24>	IEC0<24>	IPC5<28:26>	IPC5<25:24>
SPI1RX – SPI1 Receive Done	25	23	IFS0<25>	IEC0<25>	IPC5<28:26>	IPC5<25:24>
U1E – UART1 Error	26	24	IFS0<26>	IEC0<26>	IPC6<4:2>	IPC6<1:0>
U1RX – UART1 Receiver	27	24	IFS0<27>	IEC0<27>	IPC6<4:2>	IPC6<1:0>
U1TX – UART1 Transmitter	28	24	IFS0<28>	IEC0<28>	IPC6<4:2>	IPC6<1:0>
I2C1B – I2C1 Bus Collision Event	29	25	IFS0<29>	IEC0<29>	IPC6<12:10>	IPC6<9:8>
I2C1S – I2C1 Slave Event	30	25	IFS0<30>	IEC0<30>	IPC6<12:10>	IPC6<9:8>
I2C1M – I2C1 Master Event	31	25	IFS0<31>	IEC0<31>	IPC6<12:10>	IPC6<9:8>
CN – Input Change Interrupt	32	26	IFS1<0>	IEC1<0>	IPC6<20:18>	IPC6<17:16>
AD1 – ADC1 Convert Done	33	27	IFS1<1>	IEC1<1>	IPC6<28:26>	IPC6<25:24>
PMP – Parallel Master Port	34	28	IFS1<2>	IEC1<2>	IPC7<4:2>	IPC7<1:0>
CMP1 – Comparator Interrupt	35	29	IFS1<3>	IEC1<3>	IPC7<12:10>	IPC7<9:8>
CMP2 – Comparator Interrupt	36	30	IFS1<4>	IEC1<4>	IPC7<20:18>	IPC7<17:16>

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: “PIC32MX General Purpose – Features”** and **TABLE 2: “PIC32MX USB – Features”** for available peripherals.

8.0 OSCILLATOR CONFIGURATION

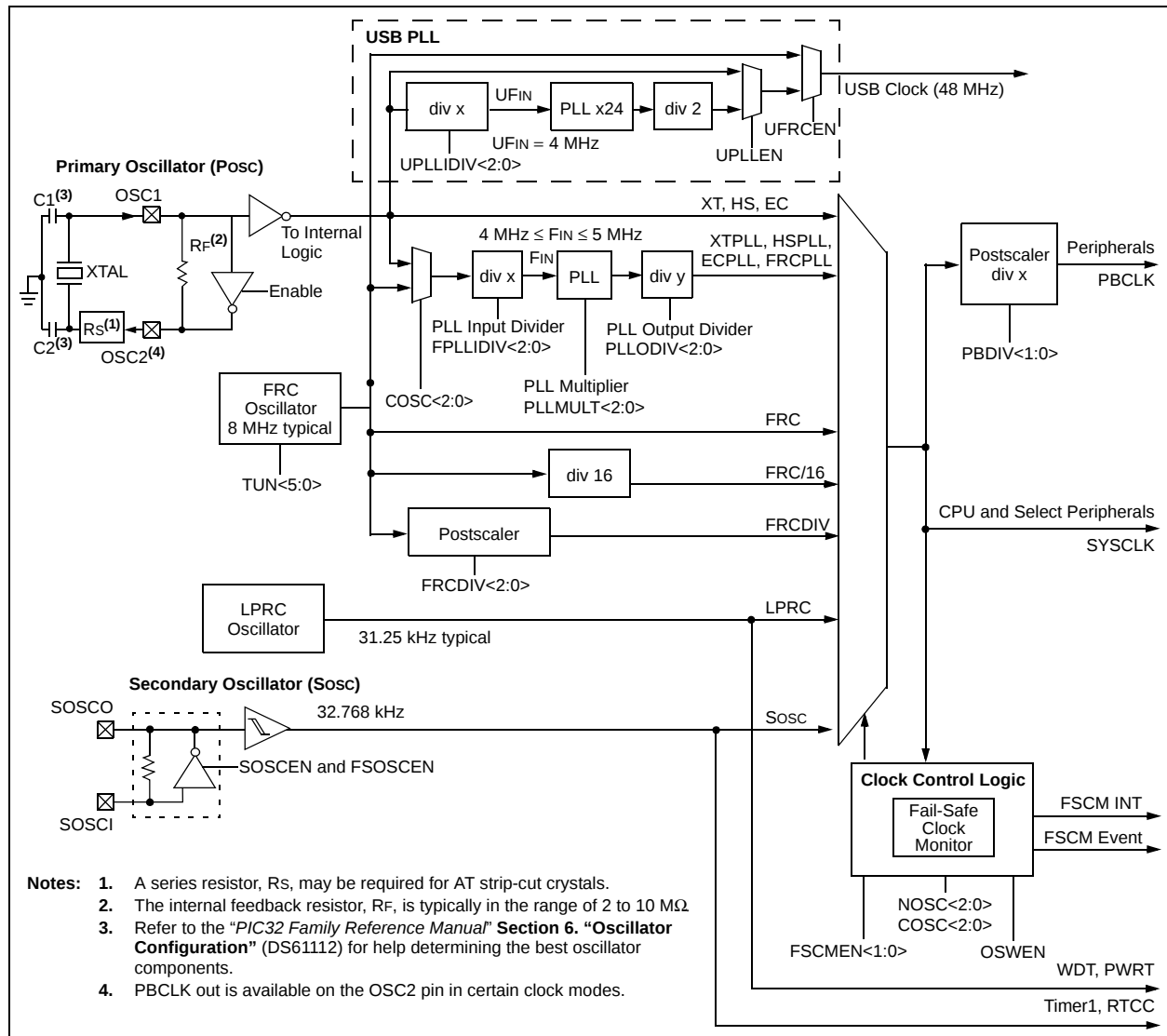
Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the “PIC32 Family Reference Manual” **Section 6. “Oscillator Configuration”** (DS61112), which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The PIC32MX oscillator system has the following modules and features:

- A total of four external and internal oscillator options as clock sources
- On-chip PLL (phase-locked loop) with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shut down
- Dedicated on-chip PLL for USB peripheral

FIGURE 8-1: PIC32MX3XX/4XX FAMILY CLOCK DIAGRAM



PIC32MX3XX/4XX

NOTES:

15.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 15. “Input Capture”** (DS61122) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Input Capture module is useful in applications requiring frequency (period) and pulse measurement. The PIC32MX3XX/4XX devices support up to five input capture channels.

The Input Capture module captures the 16-bit or 32-bit value of the selected Time Base registers when an event occurs at the ICx pin. The events that cause a capture event are listed below in three categories:

1. Simple Capture Event modes
 - Capture timer value on every falling edge of input at ICx pin
 - Capture timer value on every rising edge of input at ICx pin

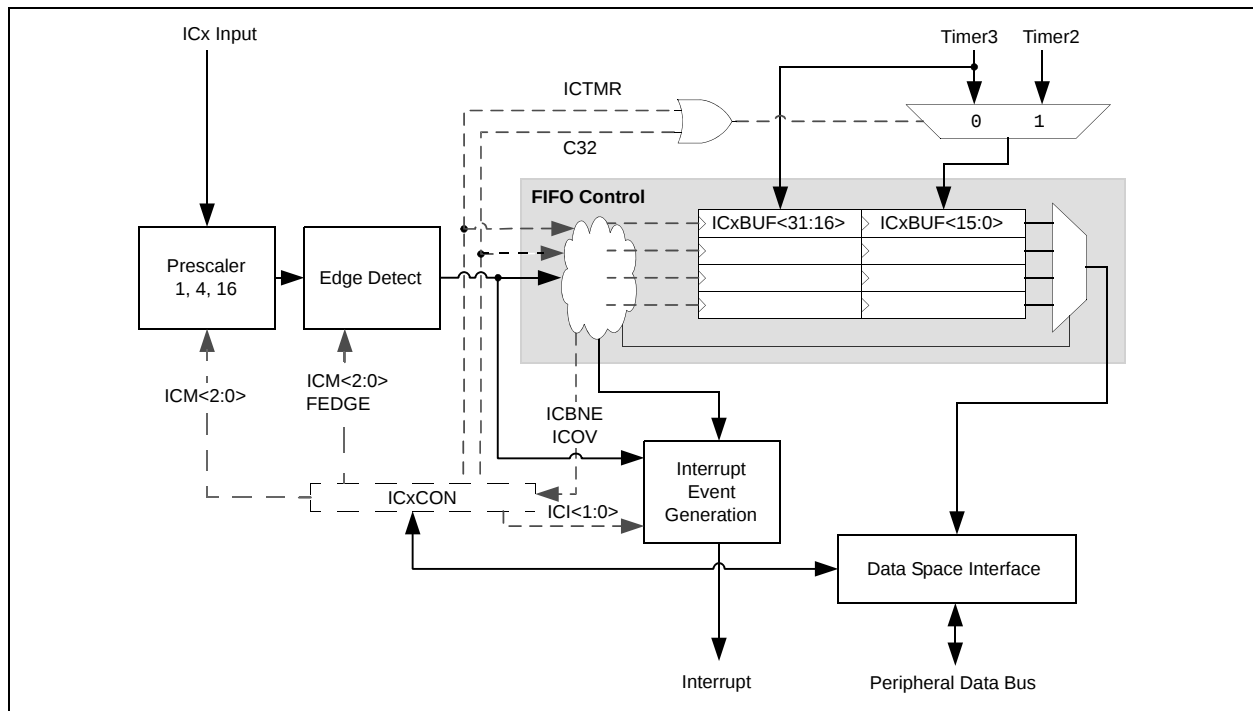
2. Capture timer value on every edge (rising and falling)
3. Capture timer value on every edge (rising and falling), specified edge first.
4. Prescaler Capture Event modes
 - Capture timer value on every 4th rising edge of input at ICx pin
 - Capture timer value on every 16th rising edge of input at ICx pin

Each input capture channel can select between one of two 16-bit timers (Timer2 or Timer3) for the time base, or two 16-bit timers (Timer2 and Timer3) together to form a 32-bit timer. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values
 - Interrupt optionally generated after 1, 2, 3 or 4 buffer locations are filled
- Input capture can also be used to provide additional sources of external interrupts

FIGURE 15-1: INPUT CAPTURE BLOCK DIAGRAM



16.0 OUTPUT COMPARE

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. “Output Compare”** (DS61111) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

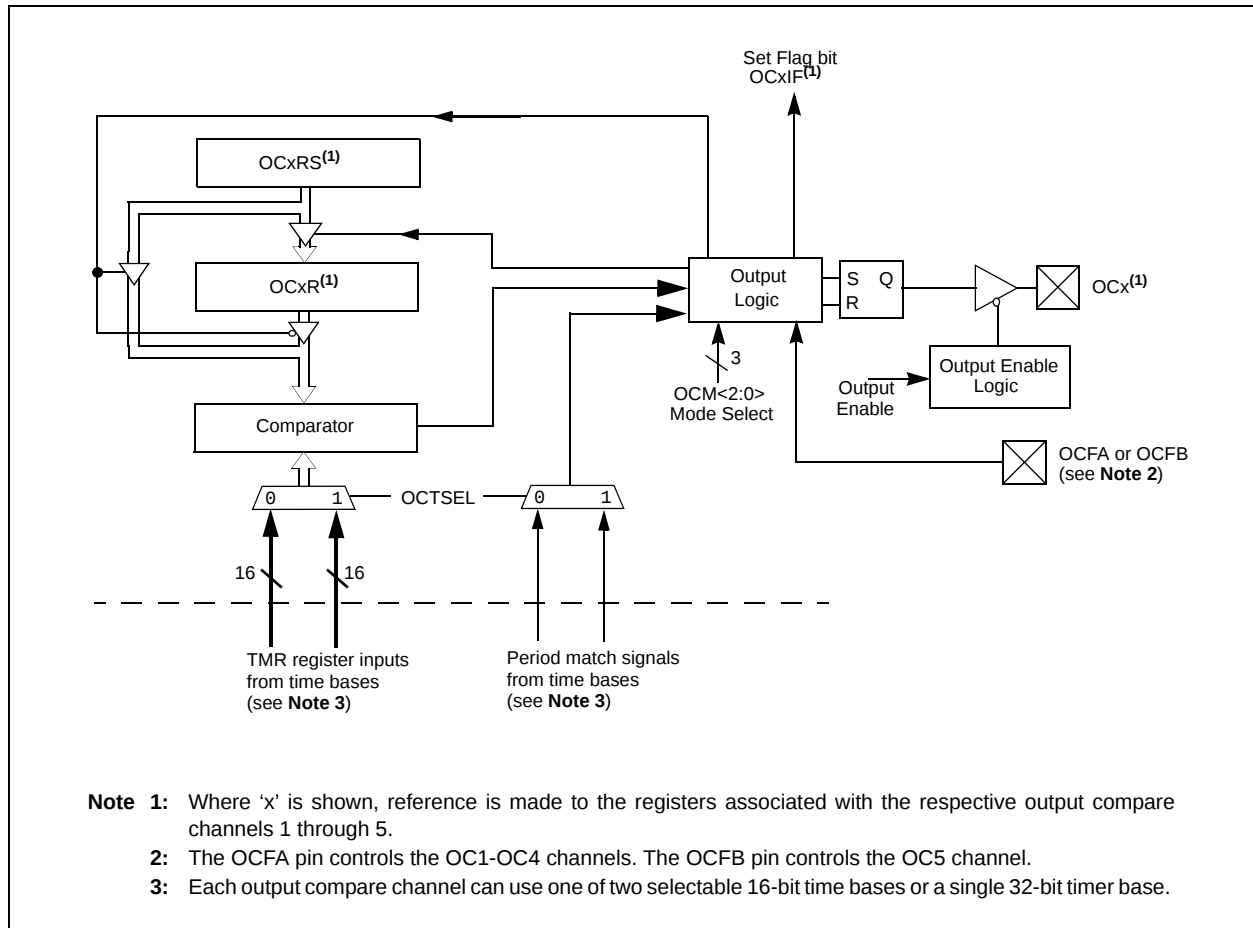
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Output Compare module (OCMP) is used to generate a single pulse or a train of pulses in response to selected time base events. For all modes of operation, the OCMP module compares the values stored in the OCxR and/or the OCxRS registers to the value in the selected timer. When a match occurs, the OCMP module generates an event based on the selected mode of operation.

The following are some of the key features:

- Multiple output compare modules in a device
- Programmable interrupt generation on compare event
- Single and Dual Compare modes
- Single and continuous output pulse generation
- Pulse-Width Modulation (PWM) mode
- Hardware-based PWM Fault detection and automatic output disable
- Programmable selection of 16-bit or 32-bit time bases.
- Can operate from either of two available 16-bit time bases or a single 32-bit time base

FIGURE 16-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



25.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. “Power-Saving Features”** (DS61130) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

This section describes power-saving for the PIC32MX3XX/4XX. The PIC32MX devices offer a total of nine methods and modes that are organized into two categories that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

25.1 Power-Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK, and by individually disabling modules. These methods are grouped into the following modes:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers.
- LPRC Run mode: the CPU is clocked from the LPRC clock source.
- Sosc Run mode: the CPU is clocked from the Sosc clock source.
- Peripheral Bus Scaling mode: peripherals are clocked at programmable fraction of the CPU clock (SYSCLK).

25.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which halt the clock to the CPU. These modes operate with all clock sources, as listed below:

- Posc Idle Mode: the system clock is derived from the Posc. The system clock source continues to operate.
Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle Mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- Sosc Idle Mode: the system clock is derived from the Sosc. Peripherals continue to operate, but can optionally be individually disabled.

- LPRC Idle Mode: the system clock is derived from the LPRC.

Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.

- Sleep Mode: the CPU, the system clock source, and any peripherals that operate from the system clock source, are halted.

Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

25.3 Power-Saving Operation

The purpose of all power-saving is to reduce power consumption by reducing the device clock frequency. To achieve this, low-frequency clock sources can be selected. In addition, the peripherals and CPU can be halted or disabled to further reduce power consumption.

25.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device Power-Saving operating modes. The CPU and most peripherals are halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep mode.

Sleep mode includes the following characteristics:

- The CPU is halted.
- The system clock source is typically shut down. See **Section 25.3.2 “Idle Mode”** for specific information.
- There can be a wake-up delay based on the oscillator selection.
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode.
- The BOR circuit, if enabled, remains operative during Sleep mode.
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode.
- Some peripherals can continue to operate in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator, e.g., RTCC and Timer 1.
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep.
- The USB module can override the disabling of the Posc or FRC. Refer to **Section 11.0 “USB On-The-Go (OTG)”** for specific details.
- Some modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption.

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REGISTER 26-6: DDPCON: DEBUG DATA PORT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-X	r-X	r-X	r-X	r-X	r-X	r-X	r-X
	—	—	—	—	—	—	—	—
23:16	r-X	r-X	r-X	r-X	r-X	r-X	r-X	r-X
	—	—	—	—	—	—	—	—
15:8	r-X	r-X	r-X	r-X	r-X	r-X	r-X	r-X
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	r-X	r-X
	DDPUSB	DDPU1	DDPU2	DDPSPI1	JTAGEN	TROEN	—	—

Legend:

R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: ('0', '1', x = Unknown)

bit 31-8 **Reserved:** Write '0'; ignore read

bit 7 **DDPUSB:** Debug Data Port Enable for USB bit
1 = USB peripheral ignores USBFRZ (U1CNFG1<5>) setting
0 = USB peripheral follows USBFRZ setting

bit 6 **DDPU1:** Debug Data Port Enable for UART1 bit
1 = UART1 peripheral ignores FRZ (U1MODE<14>) setting
0 = UART1 peripheral follows FRZ setting

bit 5 **DDPU2:** Debug Data Port Enable for UART2 bit
1 = UART2 peripheral ignores FRZ (U2MODE<14>) setting
0 = UART2 peripheral follows FRZ setting

bit 4 **DDPSPI1:** Debug Data Port Enable for SPI1 bit
1 = SPI1 peripheral ignores FRZ (SPI1CON<14>) setting
0 = SPI1 peripheral follows FRZ setting

bit 3 **JTAGEN:** JTAG Port Enable bit
1 = Enable JTAG Port
0 = Disable JTAG Port

bit 2 **TROEN:** Trace Output Enable bit
1 = Enable Trace Port
0 = Disable Trace Port

bit 1-0 **Reserved:** Write '1'; ignore read

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
TGE	Trap if Greater Than or Equal	if (int)Rs >= (int)Rt TrapException
TGEI	Trap if Greater Than or Equal Immediate	if (int)Rs >= (int)Immed TrapException
TGEIU	Trap if Greater Than or Equal Immediate Unsigned	if (uns)Rs >= (uns)Immed TrapException
TGEU	Trap if Greater Than or Equal Unsigned	if (uns)Rs >= (uns)Rt TrapException
TLT	Trap if Less Than	if (int)Rs < (int)Rt TrapException
TLTI	Trap if Less Than Immediate	if (int)Rs < (int)Immed TrapException
TLTIU	Trap if Less Than Immediate Unsigned	if (uns)Rs < (uns)Immed TrapException
TLTU	Trap if Less Than Unsigned	if (uns)Rs < (uns)Rt TrapException
TNE	Trap if Not Equal	if Rs != Rt TrapException
TNEI	Trap if Not Equal Immediate	if Rs != (int)Immed TrapException
WAIT	Wait for Interrupt	Go to a low power mode and stall until interrupt occurs
WRPGPR	Write to GPR in Previous Shadow Set	SGPR[SRSCtl _{PSS} , Rd] = Rt
WSBH	Word Swap Bytes Within Halfwords	Rd = Rt _{23..16} Rt _{31..24} Rt _{7..0} Rt _{15..8}
XOR	Exclusive OR	Rd = Rs ^ Rt
XORI	Exclusive OR Immediate	Rt = Rs ^ (uns)Immed

Note 1: This instruction is deprecated and should not be used.

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY⁽³⁾

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
Program Flash Memory							
D130	EP	Cell Endurance	1000	—	—	E/W	—
D131	VPR	VDD for Read	V _{MIN}	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	3.0	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	—
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
D136	TWW	Word Write Cycle Time	20	—	40	μs	—
	TRW	Row Write Cycle Time ⁽²⁾ (128 words per row)	3	4.5	—	ms	—
D137	TPE	Page Erase Cycle Time	20	—	—	ms	—
D138	TCE	Chip Erase Cycle Time	80	—	—	ms	—
	LVDstartup	Flash LVD Delay	—	—	6	μs	—

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the “PIC32MX Flash Programming Specification” (DS61145) for operating conditions during programming and erase cycles.

TABLE 29-12: PROGRAM FLASH MEMORY WAIT STATE CHARACTERISTICS

DC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp		
	Required Flash wait states	SYSCLK	Units
0 Wait State	0 to 30	MHz	—
1 Wait State	31 to 60		
2 Wait States	61 to 80		

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

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TABLE 29-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
OS10	Fosc	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 ⁽³⁾ 50 ⁽⁵⁾	MHz MHz	EC (Note 5) ECPLL (Note 4)
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT (Note 5)
OS12			4	—	10	MHz	XTPLL (Notes 4, 5)
OS13			10	—	25	MHz	HS (Note 5)
OS14			10	—	25	MHz	HSPLL (Notes 4, 5)
OS15			32	32.768	100	kHz	Sosc (Note 5)
OS20	Tosc	Tosc = 1/Fosc = Tcy ⁽²⁾	—	—	—	—	See parameter OS10 for Fosc value
OS30	TosL, TosH	External Clock In (OSC1) High or Low Time	0.45 x Tosc	—	—	ns	EC (Note 5)
OS31	TosR, TosF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x Tosc	ns	EC (Note 5)
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and Sosc Clock Oscillator modes)	—	1024	—	Tosc	(Note 5)
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	(Note 5)
OS42	GM	External Oscillator Transconductance	—	12	—	mA/V	VDD = 3.3V TA = +25°C (Note 5)

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

- 2:** Instruction cycle period (Tcy) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.
- 3:** 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.
- 4:** PLL input requirements: 4 MHz ≤F_{PLLIN} ≤5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.
- 5:** This parameter is characterized, but not tested in manufacturing.

FIGURE 29-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

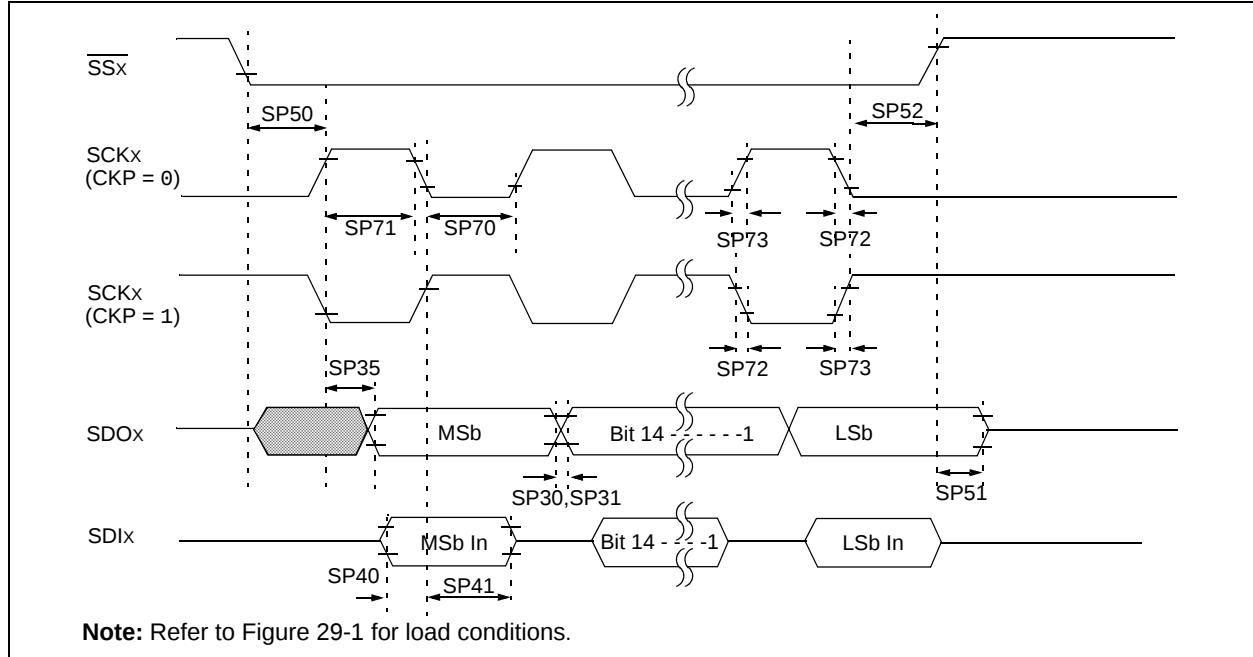


TABLE 29-30: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP70	TsCL	SCKx Input Low Time ⁽³⁾	Tsck/2	—	—	ns	—
SP71	TsCH	SCKx Input High Time ⁽³⁾	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	TsCH2DoV, TsCL2DoV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2sCH, TdiV2sCL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TsCH2diL, TsCL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2sCH, TssL2sCL	SSx ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2DoZ	SSx ↑ to SDOx Output High-Impedance ⁽³⁾	5	—	25	ns	—
SP52	TsCH2ssH, TsCL2ssH	SSx after SCKx Edge	Tsck + 20	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

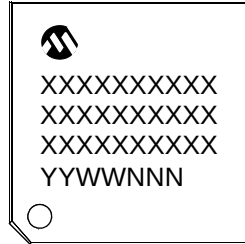
3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

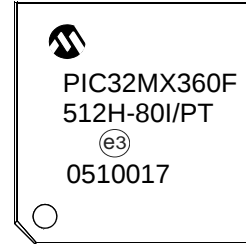
30.0 PACKAGING INFORMATION

30.1 Package Marking Information

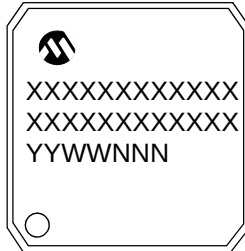
64-Lead TQFP (10x10x1 mm)



Example



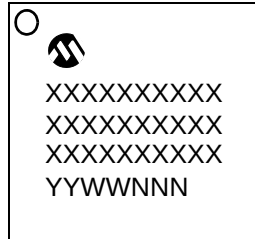
100-Lead TQFP (12x12x1 mm)



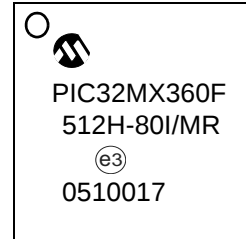
Example



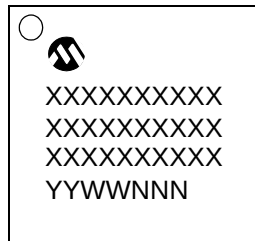
64-Lead QFN (9x9x0.9 mm)



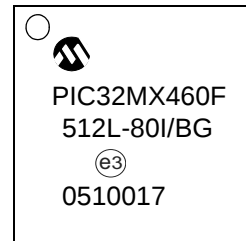
Example



121-Lead XBGA (10x10x1.1 mm)



Example



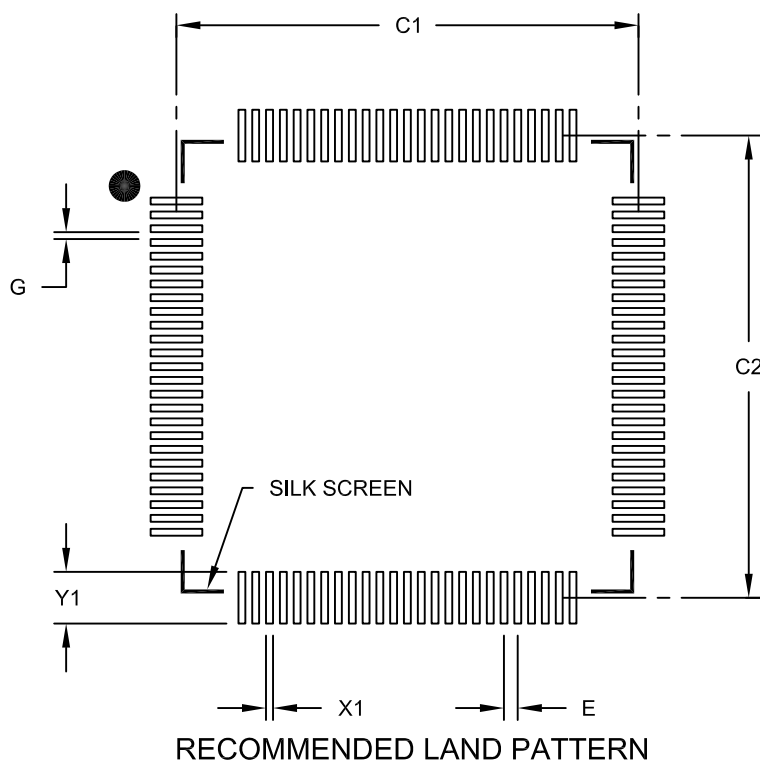
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
		Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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100-Lead Plastic Thin Quad Flatpack (PT)-12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

PIC32MX3XX/4XX

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 “Electrical Characteristics”	Updated the Absolute Maximum Ratings and added Note 3. Added Thermal Packaging Characteristics for the 121-pin XBGA package (see Table 29-3). Updated the conditions for parameters DC20, DC21, DC22 and DC23 in Table 29-5. Updated the comments for parameter D321 (CEFC) in Table 29-15. Updated the SPIx Module Slave Mode (CKE = 1) Timing Characteristics, changing SP52 to SP35 between the MSb and Bit 14 on SDOx (see Figure 29-13).
Section 30.0 “Packaging Information”	Added the 121-pin XBGA package marking information and package details.
“Product Identification System”	Added the definition for BG (121-lead 10x10x1.1 mm, XBGA). Added the definition for Speed.